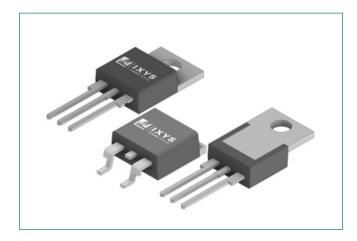
10 A High Temperature Alternistor and Standard (High Communication) Triacs







Agency Approvals and Environmental

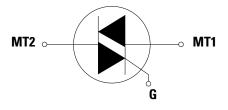
Environmental Approvals RoHS 5

Note: UL recognition agency file number E71639 (L package only)

Main Features

Characteristic	Value	Unit
I _{T(RMS)}	10	А
V_{DRM}/V_{RRM}	800	V
I _{GT (Q1)}	10 to 50	mA

Schematic Symbol



Description

This 10 A high temperature Alternistor and Standard TRIAC series. offered in TO-220AB, TO-220 isolated, and TO-263 packages, has 150 °C maximum junction temperature and 120 A ITSM (60 Hz).

This series enables easier thermal management and higher surge handling capability in AC power control applications such as heater control, motor speed control, lighting controls, and static switching relays. Alternistor TRIAC operates in quadrant I, II, and III, and offers high performance in applications requiring high commutation capability.

Features & Benefits

- Recognized to UL 1557 as an Electrically Isolated Semiconductor Device
- Glass-passivated junctions
- Surge capability up to 120 A and 60 Hz
- The L-package has an isolation rating of 2500 VRMS
- Solid-state switching eliminates arcing or contact bounce that creates voltage transients
- No contacts to wear out from

- reaction of switching events
- Restricted (or limited) RFI generation, depending on activation point sine wave
- Requires only a small gate activation pulse in each halfcycle
- RoHS compliant

Applications

- Excellent for AC switching and phase control applications such as heating, lighting, and motor speed controls. Typical applications are AC solid-state switches, light dimmers, power tools, lawn care equipment, home/brown goods, and white goods appliances.
- Alternistor Triacs (no snubber required) are used in applications with extremely inductive loads requiring highest commutation performance.
- Internally constructed isolated packages are offered for ease of heat sinking with highest isolation voltage.
- Standard type devices normally operate in Quadrants I & III triggered from AC line



10 A High Temperature Alternistor and Standard (High Communication) Triacs

Maximum Ratings — Alternistor Triac (3 Quadrants)

Symbol	Parameter	Value	Unit		
		QJ8010LHy	$T_{\rm C} = 120^{\circ} \rm C$		
I _{T(RMS)}	RMS on-state current (full sine wave)	QJ8010RHy QJ8010NHy	T _C = 130°C	10	А
1	Non repetitive surge peak on-state current	f = 50 Hz, 1	t = 20 ms	100	А
TSM	(full cycle, T _J initial = 25°C)	f = 60 Hz, t = 16.7 ms		120	А
l²t	I ² t Value for fusing	$t_{0} = 8.3 \text{ ms}$		60	A^2s
di/dt	Critical rate of rise of on-state current	$f = 60 \text{ Hz}, T_{J} = 150^{\circ}\text{C}$		70	A/µs
I _{GTM}	Peak gate trigger current	$t_p = 20 \ \mu s, T_J = 150^{\circ} C$		4	А
$P_{G(AV)}$	Average gate power dissipation	T _J = 150°C		0.5	W
T_{stg}	Storage temperature range	-		-40 to 150	°C
T_{J}	Operating junction temperature range	-		-40 to 150	°C
V_{DSM}/V_{RSM}	Peak Non-repetitive Blocking Voltage	Pulse Width	n = 100 µs	$V_{DRM}/V_{RRM} + 200$	V

Maximum Ratings — Standard Triac

Symbol	Paramet	Value	Unit		
$V_{DSM}//V_{RSM}$	Peak non-repetitive blocking voltage	Pulse Width =100 μs	800 V	$V_{DRM}/V_{RRM} + 200 V$	V
1	RMS on-state current (full sine wave)	QJxx10Ly	$T_{\rm C} = 120^{\circ}{\rm C}$	10	А
T(RMS)	nivis on-state current (run sine wave)	QJxx10Ry/QJxx10Ny	$T_{\rm C} = 130^{\circ}{\rm C}$	10	A
	Non repetitive surge peak on-state current	f = 50 Hz, t = 20 ms	QJxx10xy	100	А
TSM	(full cycle, T_J initial = 25°C)	f = 60 Hz, t = 16.7 ms	QJxx10xy	120	A
l²t	I ² t Value for fusing	$t_p = 8.3 \text{ ms}$	QJxx10xy	60	A^2s
di/dt	Critical rate of rise of on-state current $I_G = 200 \text{mA}$ with $\leq 0.1 \mu \text{s}$ rise time	f = 60 Hz, T _J =150 °C		70	A/µs
I _{GTM}	Peak gate trigger current	$t_p = 20 \mu\text{s}, T_J =$	t _p = 20 μs, T _J =150 °C		A/µs
$P_{G(AV)}$	Average gate power dissipation	T _J =150 °C		0.5	W
T_{stg}	Storage temperature range	-		-40 to 150	°C
T_{J}	Operating junction temperature range	-		-40 to 150	°C

Note: xx=voltage/10, x=package, y=sensitivity

Thermal Characteristics

Symbol	Parameter	Value	Unit	
$R_{\Theta(J-C)}$	Thermal Resistance, junction-to-case (AC)	QJ8010RHy/QJ8010NHy QJ8010Ry/QJ8010Ny		°C/W
		QJ8010LHy/QJ8010Ly	2.3	
D	The arrest Desistance is marking to employed (AC)	QJ8010RHy/QJ8010Ry	45	0000
R _{e(J-A)}	Thermal Resistance, junction-to-ambient (AC)	QJ8010LHy/QJ8010Ly	90	°C/W



10 A High Temperature Alternistor and Standard (High Communication) Triacs

Electrical Characteristics (TJ = 25°C, unless otherwise specified) — Alternistor Triac (3 Quadrants)

Symbol	Description	Conditions		QJ8010xH3		QJ8010xH3 QJ8010xH4		QJ8010xH5		Unit			
Syllibol			MIN	TYP	MAX	MIN	TYP	MAX	MIN	TYP	MAX	Onit	
I _{GT}	DC Gate Trigger Current	$V_{_{\rm D}}$ = 12 V, $R_{_{\rm L}}$ = 60 Ω	1-11-111	-	-	10	-	-	35	-	-	50	mA
$V_{\rm GT}$	DC Gate Trigger Voltage	$V_D = 12 \text{ V}, R_L = 60 \Omega$ I-II-III		-	-	1.3	-	-	1.3	-	-	1.3	V
$V_{\rm GD}$	Gate Non-trigger Voltage	$V_{D} = V_{DRM}, R_{L} = 3.3 \text{ k}\Omega, T_{J} = 150 \text{ °C}$	1-11-111	0.2	-	-	0.2	-	-	0.2	-	-	V
I _H	Holding Current	$I_{T} = 100 \text{ mA}$		-	-	15	-	-	40	-	-	50	mA
dv/dt	Critical Rate-of-rise of	$V_D = V_{DRM}$, Gate Open, $T_J = 150 ^{\circ}\text{C}$		150	-	-	450	-	-	700	-	-	V/µs
uv/ut	Off-stage Voltage	$V_D = 2/3 V_{DRM}$, Gate Open, $T_J = 150 ^{\circ} C$		200	-	-	600	-	-	1000	-	-	ν/μδ
(dv/dt)c		(di/dt)/c = 6.5 A/ms, TJ = 150 °C		10	-	-	20	-	-	30	-	-	V/µs
t _{gt}	Turn-on Time	$I_{G} = 2 \times I_{GT}, P_{W} = 15 \mu s, IT = 14.1 A$	(pk)	-	4	-	-	-	7	-	-	9	-

Electrical Characteristics (TJ = 25°C, unless otherwise specified) — Standard Triac

Comple al	Description	Canditions	ns Quadrant		Va	Value		
Symbol	bol Description Conditions Q		Quadra	ant	Qxx10x4	Qxx10x5	Unit	
	DC Cata Trigger Current	V 12V B 60.0	I - II - III	NAAV	25	50	A	
I _{GT}	DC Gate Trigger Current	$V_D = 12V R_L = 60 \Omega$	IV	MAX.	50	50	mA	
V _{GT}	DC Gate Trigger Voltage	$V_D = 12V R_L = 60 \Omega$ ALL		MAX.	1.3		V	
V_{GD}	Gate Non-trigger Voltage	$V_D = V_{DRM} R_L = 3.3 \text{ k}\Omega T_J = 150^{\circ}\text{C}$ ALL		MIN.	0.2		V	
I _H	Holding Current	$I_T = 100 \text{mA}$	$I_{T} = 100 \text{mA}$		35	50	mA	
dv/dt	Critical Rate-of-rise of Off-	$V_D = V_{DRM}$ Gate Open $T_J = 150$ °C	800V	MIN.	600	1000	\// ₁ , 10	
av/at	stage Voltage $V_D = 2/3 V_{DRM}$	$V_D = 2/3 V_{DRM}$ Gate Open $T_J = 150$ °C	8007	IVIIIN.	800	1200	V/µs	
(dv/dt)c		$(di/dt)c = 6.5 \text{ A/ms T}_J = 150^{\circ}\text{C}$		TYP.	3	4	V/µs	
	t _{gt} Turn-on Time	$I_{G} = 2 \times I_{GT} P_{W} = 15 \mu s I_{T} = 14.1 A(pk)$	1 – 11 – 111	TVD	1-2-6	1-2-6		
t _{gt}			IV	TYP.	10	11	μs	

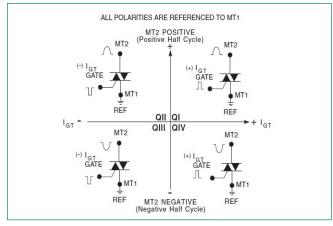
Static Characteristics

Symbol	Description	Conditions	Maximum Value	Unit
V_{TM}	Peak On-state Voltage	$I_{TM} = 14.1A t_p = 380 \mu s$	1.60	V
1 /1	Off-state Current, Peak Repetitive	$V_D = V_{DRM} = V_{RRM}$, $T_J = 25$ °C	10	μΑ
DRM / RRM		$V_D = V_{DRM} = V_{RRM}$, $T_J = 150$ °C	4	mA



10 A High Temperature Alternistor and Standard (High Communication) Triacs

Figure 1: Definition of Quadrants



Note: Alternistors will not operate in QIV

Figure 3: Normalized DC Holding Current vs. Junction Temperature

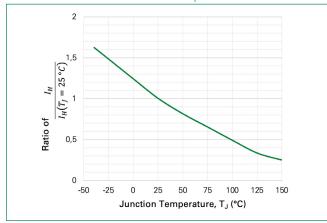


Figure 5:Power Dissipation (Typical) vs. RMS On-State Current

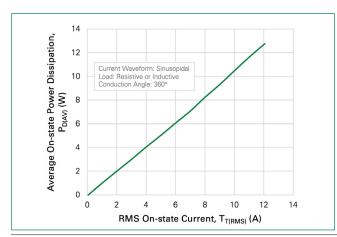


Figure 2: Normalized DC Gate Trigger Current for All Quadrants vs. Junction Temperature

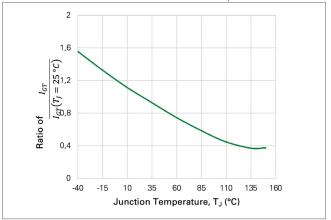


Figure 4:Normalized DC Gate Trigger Voltage for All Quadrants vs. Junction Temperature

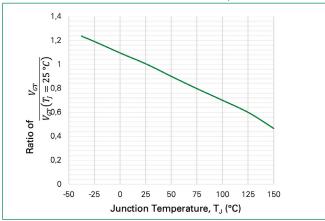
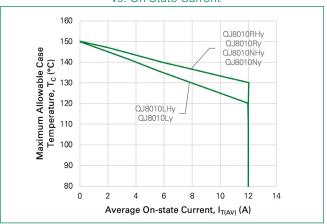
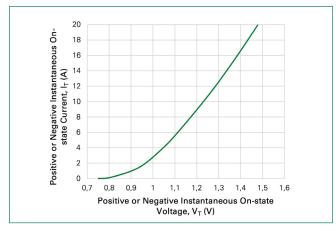


Figure 6:Maximum Allowable Case Temperature vs. On-State Current



10 A High Temperature Alternistor and Standard (High Communication) Triacs

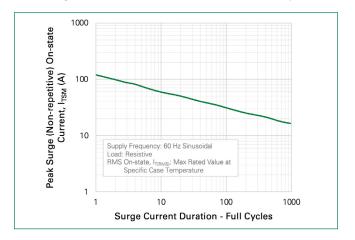
Figure 7:Typical On-state Current vs. On-state Voltage



Notes:

- 1. Gate control may be lost during and immediately following surge current interval.
- 2. Overload may not be repeated until junction temperature has returned to steady-state rated value

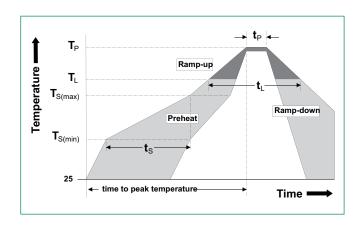
Figure 8: Surge Peak On-state Current vs. Number of Cycles



10 A High Temperature Alternistor and Standard (High Communication) Triacs

Soldering Parameters

Reflow Condi	tion	Pb – Free assembly	
	-Temperature Min (T _{s(min)})	150°C	
Pre Heat	-Temperature Max (T _{s(max)})	200°C	
	-Time (min to max) (t _s)	60 to 180 s	
Average ramp	o up rate (Liquidus Temp) (T_L) to peak	5°C/second max	
T _{S(max)} to T _L - R	T _{S(max)} to T _L - Ramp-up Rate		
Reflow	- Temperature (T _L) (Liquidus)	217°C	
	-Time (min to max) (t _s)	60 to 150 seconds	
Peak Tempera	iture (T _P)	260 °C (±5 °C)	
Time within 5	5°C of actual peak Temperature (t _p)	20 to 40 seconds	
Ramp-down I	5°C/second max		
Time 25°C to	peak Temperature (T _P)	8 minutes Max.	
Do not excee	280°C		



Physical Specifications

Terminal Finish	100% Matte Tin-plated
Body Material	UL recognized epoxy meeting flammabilty classification 94V-0.
Terminal Material	Copper Alloy

Design Considerations

Careful selection of the correct component for the application's operating parameters and environment will go a long way toward extending the operating life of the Thyristor. Good design practice should limit the maximum continuous current through the main terminals to 75% of the component rating. Other ways to ensure long life for a power discrete semiconductor are proper heat sinking and selection of voltage ratings for worst case conditions. Overheating, overvoltage (including dv/dt), and surge currents are the main killers of semiconductors. Correct mounting, soldering, and forming of the leads also help protect against component damage.

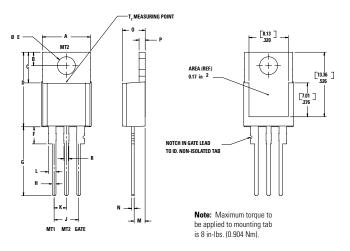
Environmental Specifications

Test	Specifications and Conditions
AC Blocking	MIL-STD-750, M-1040, Cond A Applied Peak AC voltage @ 125°C for 1008 hours
Temperature Cycling	MIL-STD-750, M-1051, 100 cycles; -40°C to +150°C, 15-min dwell-time
Temperature/Humidity	EIA/JEDEC, JESD22-A101 1008 hours; 320V - DC: 85°C; 85% rel humidity
High Temp Storage	MIL-STD-750, M-1031, 1008 hours; 150°C
Low-Temp Storage	1008 hours; -40°C
Resistance to Solder Heat	MIL-STD-750 Method 2031
Solderability	ANSI/J-STD-002, category 3 Test A
Lead Bend	MIL-STD-750, M-2036 Cond E



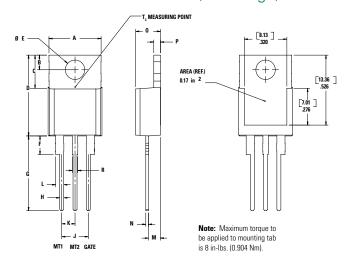
10 A High Temperature Alternistor and Standard (High Communication) Triacs

Dimensions - TO-220AB (R-Package) - Non-Isolated Mounting Tab Common with Center Lead



ъ	Milim	eters	Inches		
Dimension	Min	Max	Min	Max	
Α	0.380	0.420	9.65	10.67	
В	0.105	0.115	2.67	2.92	
С	0.230	0.250	5.84	6.35	
D	0.590	0.620	14.99	15.75	
E	0.142	0.147	3.61	3.73	
F	0.110	0.130	2.79	3.30	
G	0.540	0.575	13.72	14.61	
Н	0.025	0.035	0.64	0.89	
J	0.195	0.205	4.95	5.21	
K	0.095	0.105	2.41	2.67	
L	0.060	0.075	1.52	1.91	
M	0.085	0.095	2.16	2.41	
N	0.018	0.024	0.46	0.61	
Ο	0.178	0.188	4.52	4.78	
P	0.045	0.060	1.14	1.52	
R	0.038	0.048	0.97	1.22	

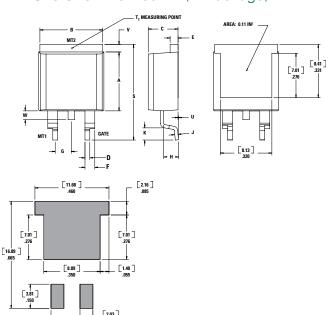
Dimensions - TO-220AB (L-Package) - Isolated Mounting Tab



Dimension	Milim	eteres	Inches		
Dimension	Min	Max	Min	Max	
Α	0.380	0.420	9.65	10.67	
В	0.105	0.115	2.67	2.92	
С	0.230	0.250	5.84	6.35	
D	0.590	0.620	14.99	15.75	
E	0.142	0.147	3.61	3.73	
F	0.110	0.130	2.79	3.30	
G	0.540	0.575	13.72	14.61	
Н	0.025	0.035	0.64	0.89	
J	0.195	0.205	4.95	5.21	
K	0.095	0.105	2.41	2.67	
L	0.060	0.075	1.52	1.91	
M	0.085	0.095	2.16	2.41	
N	0.018	0.024	0.46	0.61	
0	0.178	0.188	4.52	4.78	
P	0.045	0.060	1.14	1.52	
R	0.038	0.048	0.97	1.22	

10 A High Temperature Alternistor and Standard (High Communication) Triacs

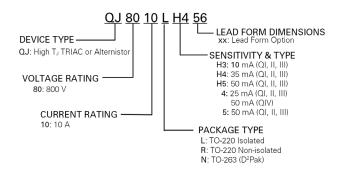
Dimensions - TO-263AB (N-Package) - D2-PAK Surface Mount



Dimension	Inches		Millimeters	
	Min	Max	Min	Max
Α	0.360	0.370	9.14	9.40
В	0.380	0.420	9.65	10.67
С	0.178	0.188	4.52	4.78
D	0.025	0.035	0.64	0.89
E	0.045	0.060	1.14	1.52
F	0.060	0.075	1.52	1.91
G	0.095	0.105	2.41	2.67
Н	0.092	0.102	2.34	2.59
J	0.018	0.024	0.46	0.61
K	0.090	0.110	2.29	2.79
S	0.590	0.625	14.99	15.88
V	0.035	0.045	0.89	1.14
U	0.002	0.010	0.05	0.25
W	0.040	0.070	1.02	1.78

Part Numbering System

_ [6.60]_



Part Marking System

TO-220 AB (L and R package)
TO-263 AB (N package)

